

PRESS RELEASE

BE Semiconductor Industries Announces 2018 Fourth Quarter and Full Year Results Release, Conference Call and Webcast Date

Duiven, the Netherlands, February 14, 2019 - BE Semiconductor Industries N.V. ("the Company" or "Besi"), (Euronext Amsterdam: BESI; OTC: BESIY, Nasdaq International Designation), a leading manufacturer of assembly equipment for the semiconductor industry, will release results for the fourth quarter and full year ended December 31, 2018, on Wednesday, February 20, 2019 at 7.00 a.m. CET (1.00 a.m. EST).

Besi will host a conference call and audio webcast (log on via <u>www.besi.com</u>) to discuss its results for the fourth quarter and full year ended December 31, 2018, on Wednesday, February 20, 2019 at 4.00 p.m. CET (10.00 a.m. EST). The teleconference dial-in number is (+31) 20 531 5851. The audio webcast will remain available on <u>www.besi.com</u>.

About Besi

Besi is a leading supplier of semiconductor assembly equipment for the global semiconductor and electronics industries offering high levels of accuracy, productivity and reliability at a low cost of ownership. The Company develops leading edge assembly processes and equipment for leadframe, substrate and wafer level packaging applications in a wide range of end-user markets including electronics, mobile internet, cloud server, computing, automotive, industrial, LED and solar energy. Customers are primarily leading semiconductor manufacturers, assembly subcontractors and electronics and industrial companies. Besi's ordinary shares are listed on Euronext Amsterdam (symbol: BESI). Its Level 1 ADRs are listed on the OTC markets (symbol: BESIY Nasdaq International Designation) and its headquarters are located in Duiven, the Netherlands. For more information, please visit our website at <u>www.besi.com</u>.

Contacts:

Richard Blickman, CEO Cor te Hennepe, SVP Finance Tel. (31) 26 319 4500 investor.relations@besi.com IR Contact Europe: Frank Jansen CFF Communications Tel. (31) 20 575 4024 besi@cffcommunications.nl